FlipChip International Breaks Ground on China Joint Venture for Wafer Level Packaging with Millennium Microtech Shanghai

Shanghai, China, February 10, 2006---FlipChip International LLC announced today that it started construction of an advanced bumping facility for a new Joint Venture in China with Millennium Microtech, Shanghai. The Joint Venture will provide wafer level packaging and flip chip bumping services to the domestic and international semiconductor market. The JV is owned respectively by FlipChip International and Millennium Microtech (Shanghai) Co., Ltd. The JV will be referred to as FCMS and be located at MMS's existing Pu Dong facility.

Bob Forcier, President and CEO of FlipChip International, stated, "We are very excited to have achieved such a stellar partner with our new FCMS China joint venture. Pu Dong is one of the most active semiconductor regions in the world and we believe the combination of MMS and FCI is a powerful entry into the Chinese market with advanced flip chip bumping and wafer level packaging. The domestic consumption of flip chip devices is expected to maintain double digit growth for the next three years and is an essential packaging technology for wireless portable devices and video phones"

"This is a logical extension of our Shanghai facility and we are proud to partner with one of the world's leading wafer bumping technology companies. We are certain that our customers will be delighted with the one-stop-shop benefits that FCI and MMS can jointly offer in advanced semiconductor packaging providing an optimum package upgrade path for emerging applications" said Vic Tee, President and CEO of Millennium Microtech.

FlipChip International, LLC is a privately held supplier of products and services for the wafer bumping and wafer scale packaging semiconductor market. FlipChip International, LLC is a wholly owned subsidiary of RoseStreet Labs LLC, a supplier of products and services for wireless infrastructure in the life science, renewable energy and homeland security markets.

MMS is a subsidiary of Millennium Microtech Holding (MMH). MMH provides fully integrated semiconductor packaging and test services including dicing, tape & reel, wafer probing and back-grinding through MMS and Millennium Microtech (Thailand) Co., Ltd.

For further information contact: Stephanie Perry FlipChip International, LLC 602-431-4747 stephanie.perry@flipchip.com

website: www.flipchip.com

Patraporn Jarupat Millennium Microtech Holding Corporation +663-884-5560 patrapornja@m-microtech.com

website: www.m-microtech.com